



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#7/B  
10-27-92  
PATENT HP  
10-28-92 HP

In re application of

Art Unit 3102

Richard S. Ketcham

Serial No. 07/628,440

Filed: December 14, 1990

For: OPTIMIZED PIEZOELECTRIC  
RESONATOR-BASED NETWORKS  
AND ASSOCIATED METHOD

Date: October 13, 1992

Examiner: M. Budd

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AMENDMENT

TO THE COMMISSIONER  
OF PATENTS AND TRADEMARKS:

In response to the Office action dated July 13, 1992,  
please amend the above-identified patent application as follows:

In the Specification:

Page 1, lines 9 and 10, delete "without the need for  
additional interconnects to complete connections", replace with  
--with interconnects on one or either principal face of a  
piezoelectric plate or membrane--.

*B1*  
Page 1, line 23, after "wafers" add --plates, or  
films--.

*B2*  
Page 1, line 24, delete "Through" and replace with  
--These thin structures may be formed by thin film deposition  
onto a suitable substrate which leaves one principal surface of  
the material relatively inaccessible for interconnects.

*B3*  
Resonators may be fabricated from these thin films and through--.

Page 2, line 26, at end add --The situation is further  
complicated by the desirability of production testing as many as  
600 piezoelectric resonator networks on each 4-inch-diameter  
wafer substrate prior to final assembly. Microwave probe testing